



Fast Recovery Glass Passivated Rectifiers

Features

- Fast switching for high efficiency
- Low cost
- Glass Passivated Chip
- Low reverse leakage current
- Low forward voltage drop
- High current capability
- The plastic material carries UL recognition 94V-0

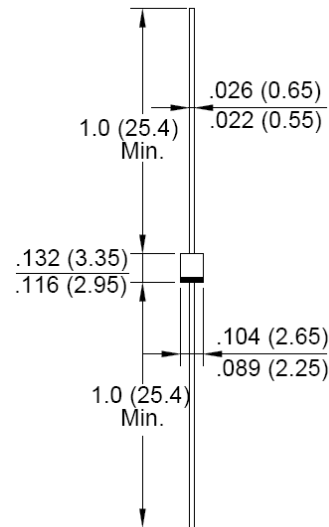
Mechanical Data

- Case: JEDEC R-1 molded plastic
- Polarity: Color band denotes cathode
- Mounting position: Any

Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

Reverse Voltage - 50 to 1000 Volts
Forward Current - 1.0 Amperes

R-1



RoHS
COMPLIANT

Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristics	Symbol	1F1G	1F2G	1F3G	1F4G	1F5G	1F6G	1F7G	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @T _A =75℃	I _(AV)	1.0							A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	I _{FSM}	30							A
Peak Forward Voltage at 1.0A DC	V _F	1.3							V
Maximum DC Reverse Current @T _J =25℃ at Rated DC Blocking Voltage @T _J =100℃	I _R	5.0 100							μA
Maximum Reverse Recovery Time (Note 1)	T _{rr}	150				250	500		nS
Typical Junction Capacitance (Note2)	C _J	25				15			pF
Typical Thermal Resistance Junction to Ambient	R _{θJA}	25							℃/W
Operating Junction Temperature Range	T _J	-55 to +150							℃
Storage Temperature Range	T _{STG}	-55 to +150							℃

Notes: 1. Measured with I_F=0.5A, I_R=1A, I_{RR}=0.25A .

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC

3. The typical data above is for reference only.



Fig. 1 - Forward Current Derating Curve

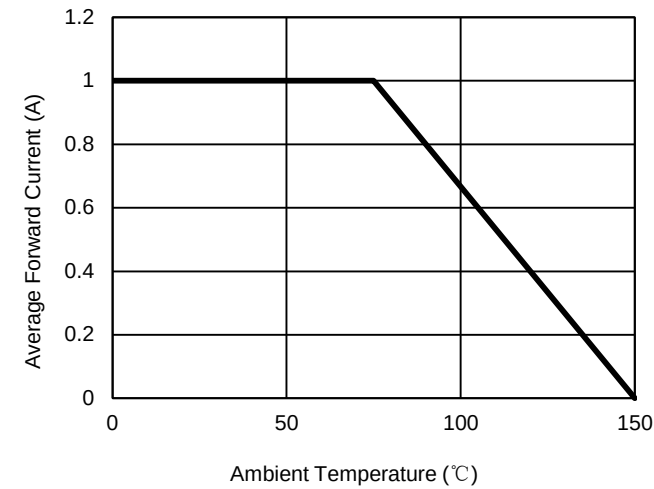


Fig. 2 - Maximum Non-Repetitive Surge Current

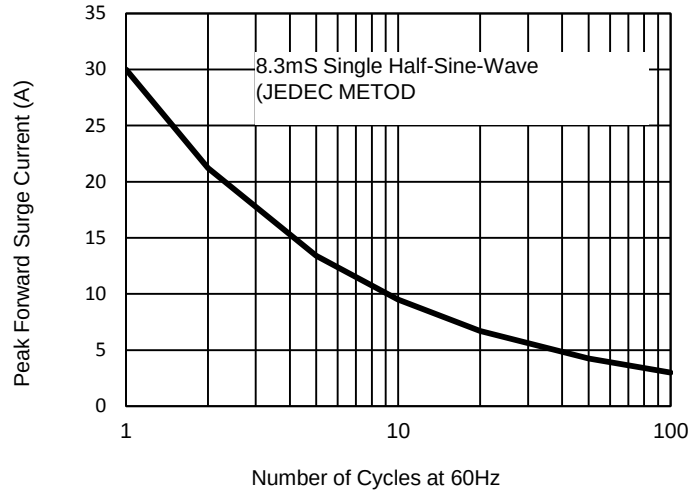


Fig. 3 - Typical Junction Capacitance

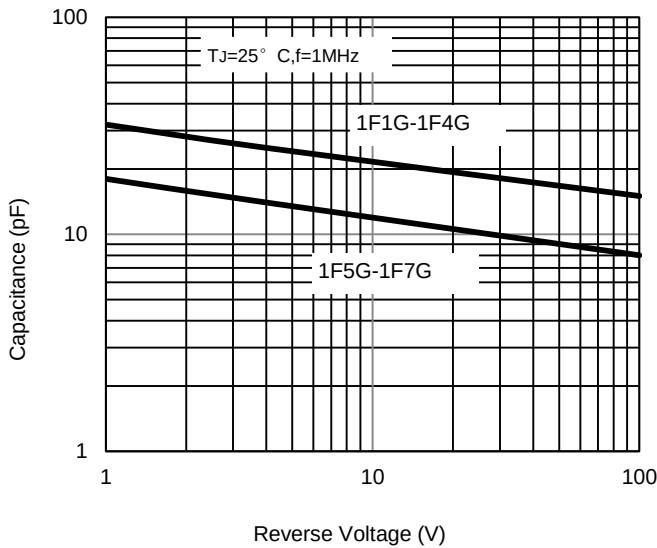
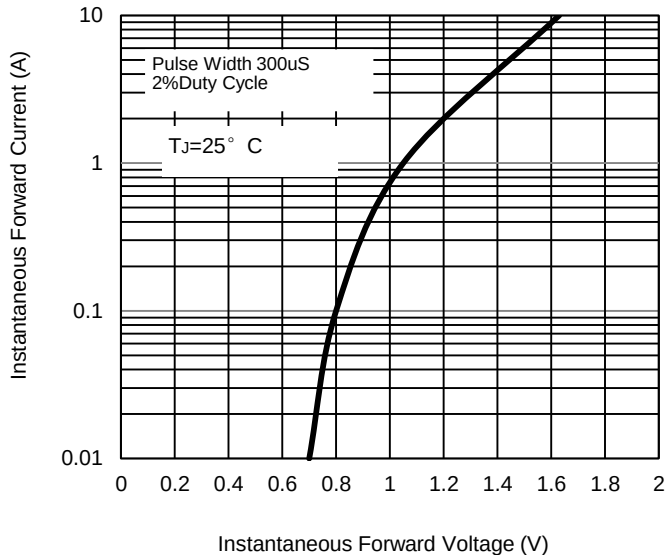


Fig. 4 - Typical Forward Characteristics





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